

SEALABLE RESIN SHEET AND ELECTRONIC COMPONENT DEVICE

ABSTRACT

The present invention provides a sealable resin sheet for resin-sealing electronic component chips mounted on a base material in a state of facing the base material through a gap. The sealable resin sheet is suitable to achieve excellent hollow encapsulation even when the ratio of the mounting height to the mounting interval between the electronic component chips is high. The present invention also provides an electronic component device including an electronic component chip sealed with the sealable resin sheet of the present invention.

The sealable resin sheet X of the present invention includes a sealable resin layer 11 and a sealable resin layer 12 sequentially in the thickness direction D. The sealable resin layer 11 includes a first thermosetting resin and a first inorganic filler, and has an average coefficient of thermal expansion of 20 ppm/°C or less after being cured. The sealable resin layer 12 includes a second thermosetting resin and a second inorganic filler, and has an average coefficient of thermal expansion of 20 ppm/°C or less after being cured. The content ratio of the first inorganic filler in the sealable resin layer 11 differs from the content ratio of the second inorganic filler in the sealable resin layer 12. The ratio of the thickness of the sealable resin layer 11 to the entire thickness of the sealable resin sheet X is 0.37 to 0.82.

FIG. 1